

TECHNICAL INFORMATION

KB-7152 (ANSI: CEM-3)

无卤素覆铜箔玻璃毡布复合基层压板

Features 特 点

- 无卤素, 溴及氯元素含量小于 900ppm;溴+氯含量小于 1500ppm Halogen-free, Br/Cl content below 900ppm; Br+Cl content below 1500ppm
- 不含锑及红磷,燃烧时不残留有毒成分 Antimony and red phosphor free, Absence of highly toxic dioxins in burning exhaust gas.
- 符合 IPC-4101D/ 14 的规范要求
 IPC-4101D/ 14 specification is applicable.

General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Method (IPC-TM-650) 测试方法	Test Condition 处理条件	Specification (IPC-4101D) 规格值	Typical Value 典型值
Peel Strength (1 oz.)	N/mm	2.4.8	125℃	AABUS	1.3
铜箔剥离强度	19/111111		Float 260°C / 10 Sec	AABUS	1.1
Thermal Stress 热应力	Sec	2.4.13.1	Float260°C/unetched	≥10	50
Bow / Twist 弯弓度/翘曲度	%	2.4.22.1	A	≤ 1.0	0.5 / 0.85
Flexural Strength 抗弯强度	N/mm ²	2.4.4	Length direction	≥276	368
	19/111111		Cross direction	≥186	286
Flammability 燃烧性	Rating	UL94	UL94	UL94 V-0	V-0
Surface Resistivity 表面电阻	ΜΩ	2.5.17.1	C-96/35/90	\geqslant 1.0 \times 10 ⁴	1.0×10 ⁶
Volume Resistivity 体积电阻	MΩ-cm	2.5.17.1	C-96/35/90	\geqslant 1.0 \times 10 ⁶	1.0×10 ⁷
Dielectric Constant 介电常数	_	2.5.5.2	Etched/@1 MHZ	€5.4	4.3
Loss Tangent 介质损耗	_	2.5.5.2	Etched/@1 MHZ	≤0.035	0.02
Arc Resistance 耐电弧性	Sec	2.5.1	D-48/50+D-0.5/23	≥60	120
Moisture Absorption 吸水率	%	2.6.2.1	D-24/23	≤0.5	0.15
Comparative Tracking Index 相比漏电起痕指数	V	IEC 60112	Etched/0.1% NH ₄ CL	≥175	175/600

Remarks: Specimen Thickness:1.6mm 1/1 样品厚度: 1.6mm 1/1

- A = Keep the specimen originally without any process 保持原样,不作处理
- C = Temperature and humidity conditioning 在恒温恒湿的空气中处理
- D = Immersing in distilled water with temperature control.浸在恒温的水中处理
- E = Temperature conditioning 在恒温的空气中处理

Version: 5.1

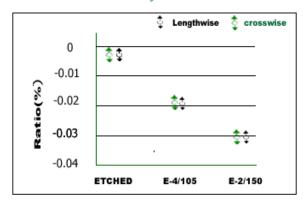


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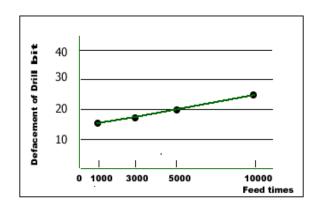
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Speciality Chart 板材特性图

Dimensional stability 尺寸稳定性



Drilling processability 钻孔加工性



应用领域

● 光电照明、 电源基板、电视机、 冰箱、洗衣机、电子乐器

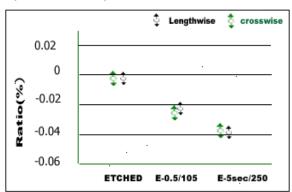
Purchasing Information 采购信息

Base Color	Thickness	Copper Cladding	Regular Size(mm)
基材颜色	厚度	铜箔厚度	常规尺寸
淡黄色 (Pale Yellow)	0.8mm ~1.6mm	18μm 35μm 70μm	

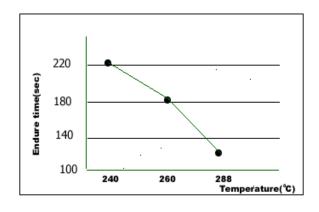
Note: Other sheet size and thickness could be available upon request.

可根据客户要求提供其它尺寸和厚度

Dimensional stability–PCB process (size:360*310mm)



Solder Resistance 耐焊性



Applications

• Photoelectricity, Power supply, TV, Refrigerator, Washing machine, Electronic musical instrument.

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